NOTES

1. CO-PLANARITY IS WITHIN 0.08 mm.
2. PLATING:
   CONTACT AREA: GOLD 0.75 μm MIN.
   LEAD AREA: GOLD 0.25 μm MIN.
   UNDER PLATING: NICKEL 2 μm MIN.
3. PER REEL: 3600 pcs.
4. INTERFACE DIMENSIONS CONFORM TO USB2.0 SPECIFICATION.
5. AS FOR PART No.1, THE PERFORMANCE REMAINS GOOD EVEN IF THERE ARE RUBBING MOUNTS BY THE ASSEMBLY PROCESS.
   AND THE PERFORMANCE REMAINS GOOD THOUGH THER MOE BE A DIFFERENCE IN THE PLATING LIQUOR BETWEEN EACH PLATING SUBCONTRACT COMPANIES.
6. AS FOR PART No.2-A PART OF SHAPE MAY BECOME DIFFERENT DEPENDING ON THE PRODUCTION METHOD.
7. CODE CONFIGURATION IS SHOWN IN FIG.1.